0.8A UMB
0.8A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

100V~1000V 0.8A
Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V, Forward Current: 0.8A, Designed for Surface Mount Application. HF product.

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General purpose.

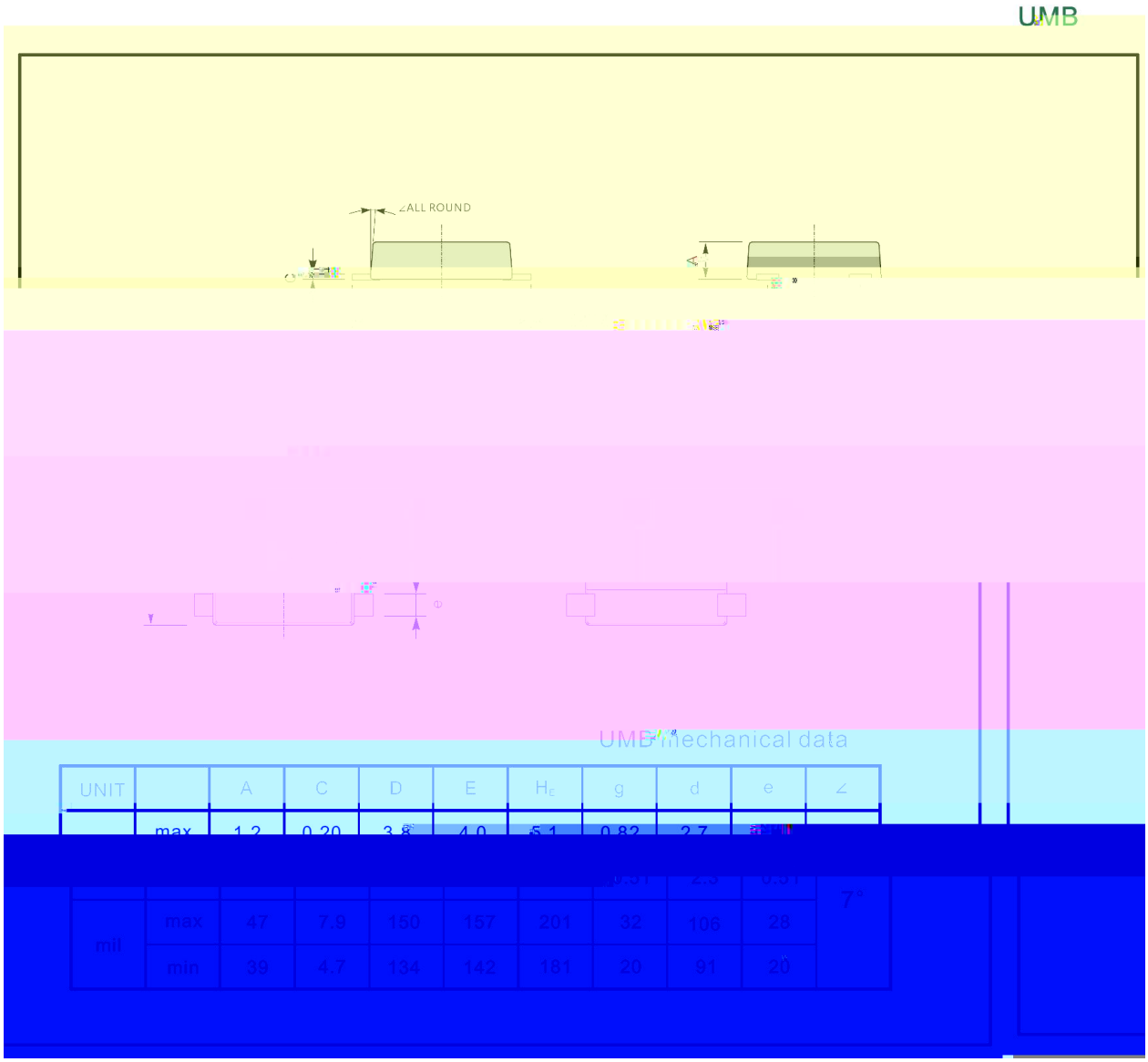
Parameter	Symbol	Rating						Unit
		UM1B	UM2B	UM4B	UM6B	UM8B	UM10B	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 40	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	$R_{\theta JA}$	110						/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5 x1.5 (3.81x3.81cm) copper pad areas.

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	I_F=0.4A		

/ Package Dimensions



UNIT		A	C	D	E	H_E	g	d	e	∠
mil	max	47	7.9	150	157	201	32	106	28	7°
	min	39	4.7	134	142	181	20	91	20	

/ Marking Instructions

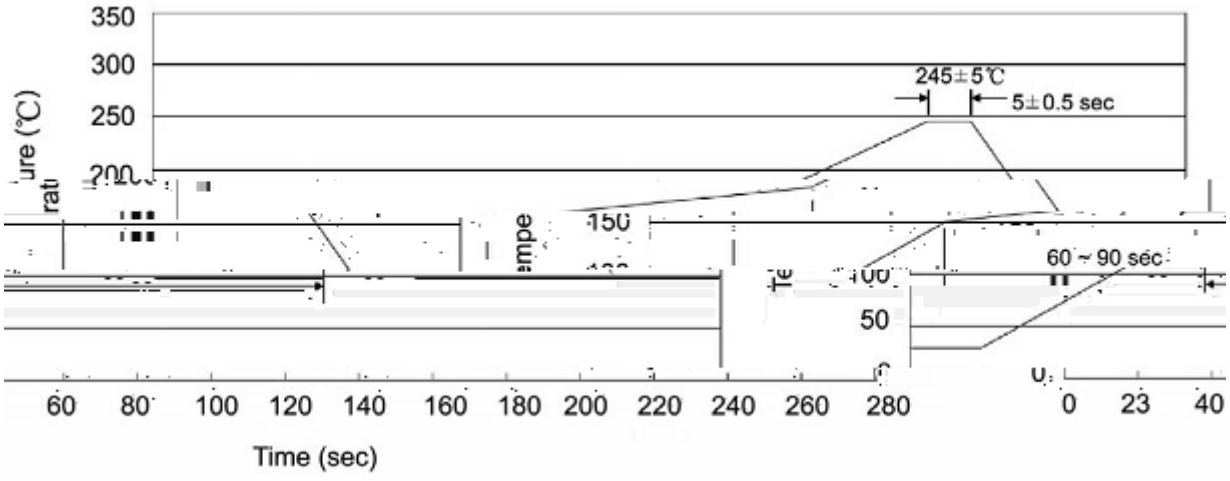
UM1B
**** 1 * 3 *

Note:

UM1B Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 *

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1	25	150	60	90sec;	1.Preheating:25~150 , Time:60~90sec.
2	245±5			5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box